

WHAT IS CLAIMED IS:

1. A method of fabricating a micromechanical structure, the method comprising:
fabricating at least two micromechanical structures on a substrate;
overcoating said micromechanical structures with a protective layer;
overcoating said protective layer with a brittle layer; and
sawing said brittle layer and said protective layer.
2. The method of Claim 1, said fabricating comprising fabricating at least two micromechanical devices on a semiconductor substrate.
3. The method of Claim 1, said fabricating comprising fabricating at least two micromirror devices on said substrate.
4. The method of Claim 1, said fabricating comprising fabricating at least two micromirror devices on a semiconductor substrate.
5. The method of Claim 1, said fabricating comprising fabricating at least two micromirror arrays on said substrate.
6. The method of Claim 1, said fabricating comprising fabricating at least two micromirror arrays on a semiconductor substrate.
7. The method of Claim 1, said overcoating with a protective layer comprising overcoating with a plastic layer.
8. The method of Claim 1, said overcoating with a protective layer comprising overcoating with a polymer resin.
9. The method of Claim 1, said overcoating with a protective layer comprising overcoating with a PARYLENE layer.

10. The method of Claim 1, said overcoating with a protective layer comprising overcoating with a acrylate monomer layer.
11. The method of Claim 1, said overcoating with a protective layer comprising overcoating with a acrylate oligomer layer.
12. The method of Claim 1, said overcoating with a protective layer comprising applying a protective overcoat by vapor deposition.
13. The method of Claim 1, said overcoating with a protective layer comprising applying a protective overcoat by immersing said substrate in a liquid protective overcoat material.
14. The method of Claim 1, said overcoating with a protective layer comprising applying a protective overcoat by spinning-on a protective overcoat layer.
15. The method of Claim 1, comprising:
thermally curing said protective layer.
16. The method of Claim 1, comprising:
curing said protective layer using ultraviolet light.
17. The method of Claim 1, said overcoating with a brittle layer comprising overcoating with a photoresist layer.
18. The method of Claim 1, said overcoating with a brittle layer comprising overcoating with a photoresist layer, further comprising:
baking said photoresist layer.
19. The method of Claim 1, said overcoating with a brittle layer comprising overcoating with a photoresist layer, further comprising:
deep UV hardening said photoresist layer.

20. The method of Claim 1, said overcoating with a brittle layer comprising overcoating with a brittle layer to prevent said protective layer from delaminating from said substrate.
21. The method of Claim 1, said sawing comprising sawing through said protective and overcoat layers.
22. The method of Claim 1, said sawing comprising sawing through said protective and overcoat layers and said substrate to separate said micromechanical devices.
23. The method of Claim 1, said sawing comprising sawing through said protective and overcoat layers and partially through said substrate layer.

TI-30637-1003